

JSR Post CMP Cleaning Solution

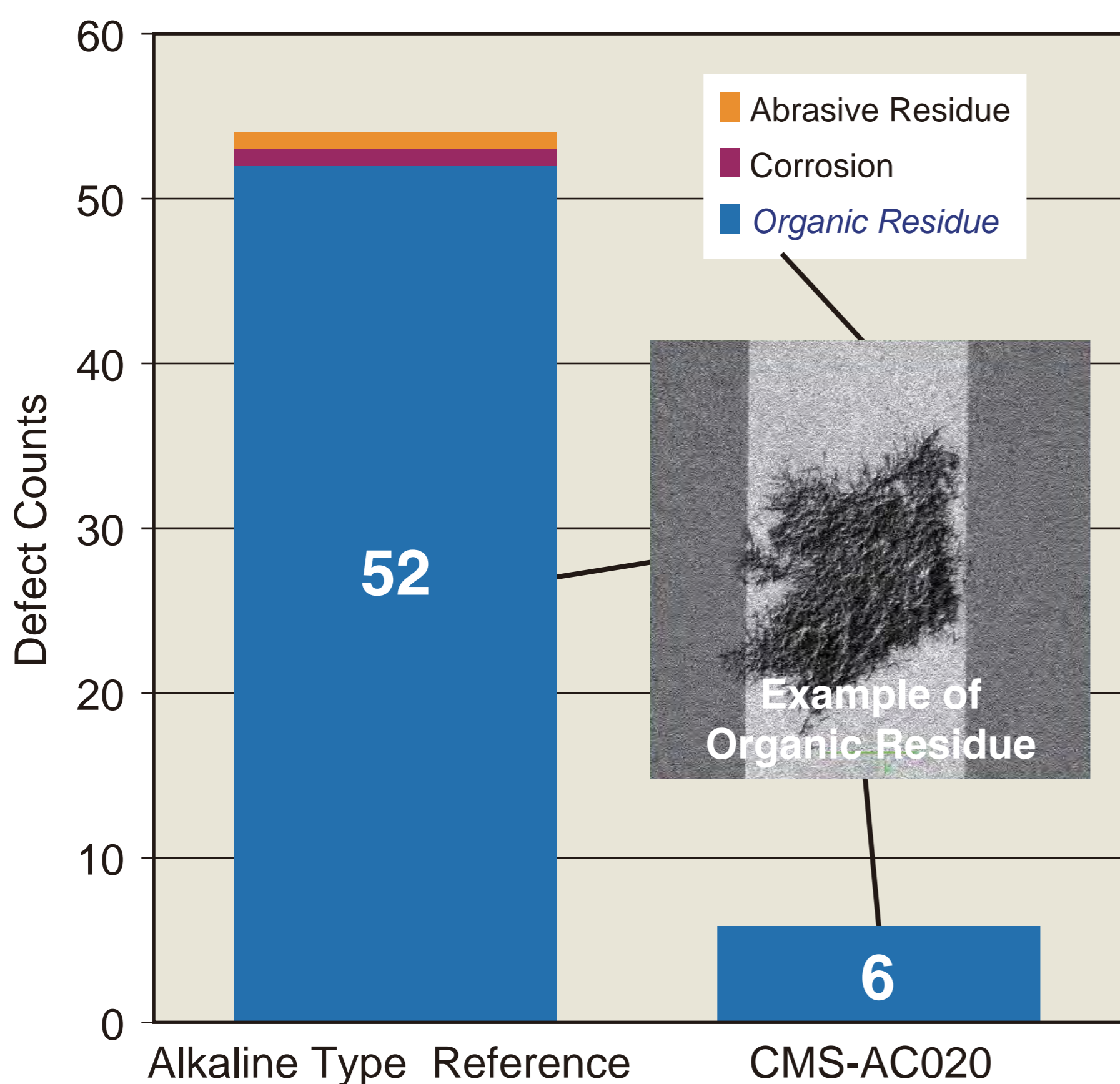
Technology Trend & JSR Cleaning Solutions

Technology Node (nm)	≥ 32	28	20	16-14	10	7-5 ≥
Barrier Metal Type	Ta/TaN		Ta/TaN, Co		Co, Ru?, Mn?	
Cleaner Trend	Acid type		Alkaline type			
JSR Post Cu CMP Cleaning Solution						
CMS-AC010	→		→ For Memory Application +Co/Ru Compatible			
CMS-AC020	→		→			

Typical Properties & Performance

Concept & Typical Properties	
Cleaning Solution	CMS-AC020
Design Concept	<ul style="list-style-type: none"> ● No TMAH type chemicals ● Polymer type metal protector is applied
pH	13 (as product) → 11(as POU)
Properties of cleaning solution	
Cu Etching Rate [Å/min]	0.4
Co Etching Rate [Å/min]	0.3
Ru Etching Rate [Å/min]	0

Defectivity of Cu/Ta Type Patterned Wafer



SEM Image of Cleaned Cu Lines

